

Subst. Form PTO-1449 APPLICANT'S INFORMATION DISCLOSURE STATEMENT	Atty. Docket No.: 2802-257-032	Serial No.:
	Applicant: Michael Bunyan, et al	
	Filing Date: Concurrently Herewith	Group:

## U.S. PATENT DOCUMENTS

Initial*		Document No.	Date	Name	Class	Subcl.	Filing Date
AA		3,928,907	12/30/75	Chisholm			
AB		4,602,678	07/29/86	Fick			
AC		4,654,754	03/31/87	Daszkowski			
AD		4,685,987	08/11/87	Fick			
AE		4,842,911	06/27/89	Fick			
AF		4,869,954	09/26/89	Squitieri			
AG		5,060,114	10/22/91	Feinberg, et al			
AH		5,061,549	10/29/91	Shores			
AI		5,167,851	12/01/92	Jamison, et al			
AJ		5,250,209	10/05/93	Jamison, et al			
AH		5,372,883	12/13/94	Shores			
AI		5,471,027	11/28/95	Call, et al			
AJ		5,533,256	07/09/96	Call, et al			
AK		5,545,475	08/13/96	Ameen, et al			
AL		5,679,457	10/21/97	Bergerson			
AM		5,781,412	07/14/98	de Sargo			
AN		5,930,893	08/03/99	Eaton			

## FOREIGN PATENT DOCUMENTS

	Document No.	Date	Country	Class	Subcl.	Translation?
AO						
AP						

## OTHER PRIOR ART

AQ	International Application Published Under the Patent Cooperation Treaty in International Publication Number WO96/37915; published 28 November 1996
AR	<del>Notification of Transmittal of International Search Report in International Application No. PCT/IB97/00223; International Filing Date 14 February 1997.</del>
AS	<del>Notification of Transmittal of International Search Report in International Application No. PCT/US99/20750; International Filing Date 9 September 1999.</del>
AT	<del>Letter dated July 25, 2000 from Eugene Lieberstein of Anderson Kill &amp; Olick, P.C.</del>
AU	Article entitled "Thermally Conductive Adhesives for Electronic Packaging, authored by Carol Latham, President of Thermagon, Inc. dated July 1991.
AV	Technical Data Sheet Ablefilm® 5025E, dated March, 1992 of Ablestik, entitled Electrically Conductive Adhesive Flm.
AW	Technical Data Sheet Ablefilm® 563K, dated November, 1995 of Ablestik, entitled Thermally Conductive Adhesive Film.
AX	Technical Data Sheet Ablefilm® 566K, dated November, 1995 of Ablestik, entitled Low Temperature Cure Adhesive Film.
AY	Article entitled T-gon 100 Series, Thermally Conductive Epoxy Adhesive Films, dated June 10, 1997 of Thermagon, Inc.
AZ	<del>Invoices dated May 15, 1992 and July 6, 1993 of Thermagon, Inc.</del>

Temporary  
Prior Art

<del>BA</del>	Letter dated August 17, 2000 from Clement A. Berard of Dann, Dorfman, Herrell & Skillman
BB	AI Technology Data Sheet for Cool-Pad TP7015, revised February, 1992.
BC	AI Technology Data Sheet for Cool-Pad TP7608, revised February, 1992.
BD	AI Technology Data Sheet for Cool-Pad TP7208, revised February, 1992.
BE	AI Technology Data Sheet for Cool-Paid TP7205, revised February, 192.
BF	AI Technology Data Sheet for Thermoplastic TP7165, revised October, 1994.
BG	AI Technology Data Sheet for Cool-Pad TP7605, revised October, 1994.
BH	AI Technology Data Sheet for Cool-Pad TP7609, revised August 12, 2000.
BI	Article authored by L.M Leung and K. K. T. Chung entitled Zero-stress Film Adhesive for Substrate Attach, published in Hybrid Circuits NO. 18, January 1989.
BJ	AI Technology Invoice No. 6420 dated February 12, 1993.
BK	AI Technology Invoice No. 7344 dated August 27, 1993.
BL	AI Technology Invoice No. 5657 dated September 14, 1992.
BM	AI Technology Invoice No. 4580 dated March 24, 1993.
BN	AI Technology Invoice No. 5370 dated July 27, 1992.
BO	AI Technology Invoice No. 4964 dated May 27, 1992.
BP	AI Technology Invoice No. 8303 dated March 18, 1994.
BQ	AI Technology Invoice No. 8789 dated July 18, 1994.
BR	AI Technology Invoice No. 6420 dated February 12, 1993.
Examiner:	Date Considered: 10/16/2001

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if in conformance and not considered. Include copy of this form with next communication to applicant.

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